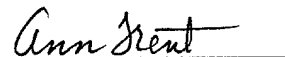


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Curran, et al. Docket No: TI-29038
Serial No: To be Assigned Examiner: TBD
Conf. No: To be Assigned Art Unit: TBD
Filed: 10/26/2001
For: METHOD AND SYSTEM FOR REDUCING THICKNESS OF SPIN-ON GLASS ON
SEMICONDUCTOR WAFERS

Assistant Commissioner for Patents
Washington, DC 20231

"EXPRESS MAIL" Mailing Label No. EL645458870US.
I hereby certify that the above correspondence is being
deposited with the U.S. Postal Service with sufficient
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service under 37 CFR 1.10 and is addressed to: Assistant
Commissioner for Patents, Washington, DC 20231 on
10-26-01.


Ann Trent

PRELIMINARY AMENDMENT

Dear Sir:


Prior to the examination of the above identified application, please amend the
specification by inserting before the first line the sentence:

--This application claims priority under 35 USC § 119(e)(1) of provisional
application Serial No. 60/248,170, filed November 13, 2000.--

Should the Examiner have any comments or suggestions concerning this
application, it is respectfully requested that the Examiner contact the undersigned in
order to expeditiously resolve any outstanding issues.

To the extent necessary, Applicants petition for an Extension of Time under 37 CFR 1.136. Please charge any fees in connection with the filing of this paper, including extension of time fees, to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,



Peter K. McLarty
Agent for Applicants
Reg. No. 44,923

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